

#21/D

1-14-03

Mulwa

PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Toshiyuki NAKAYAMA

Group Art Unit: 2815

Application No.: 09/582,351

Examiner: C. Chu

Filed: August 11, 2000

Docket No.: 106386

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURE
THEREOF, CIRCUIT BOARD AND ELECTRONIC INSTRUMENT

AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the October 8, 2002, Office Action, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 16, lines 7-15:

D' This embodiment is constructed as described above, and the method of manufacture thereof is now described. First, on the base material of the substrate 10, the leads 12 and film 14 are formed. The leads 12 and film 14 can be formed in separate processes, but are preferably formed in the same process. For example, a conductive foil such as a metal foil can be formed on the base material of the substrate 10, and this can be etched to form the leads 12 and film 14 together.